

Surface Mountable PTC Resettable Fuse: FSMD1812 Series

1. Summary

(a) RoHS Compliant & Halogen Free

(b) Applications: All high-density boards

(c) Product Features: Small surface mountable, Solid state, Faster time to trip than

standard SMD devices, Lower resistance than standard SMD devices

(d) Operation Current: 0.10A~3.00A(e) Maximum Voltage: 6V~60VDC

(f) Temperature Range: -40°C to 85°C

2. Agency Recognition

UL: File No. E211981 C-UL: File No. E211981

TÜV: File No. R50004084, R50090556

3. Electrical Characteristics (23°C)

Dowt	Hold	Trip	Rated	Max.	Typical	Max. Tim	e to Trip	Resis	tance
Part	Current	Current	Voltage	Current	Power	Current	Time	R _{MIN}	R1 _{MAX}
Number	I _H , A	I _T , A	V _{MAX} , V _{DC}	I _{MAX} , A	Pd, W	Amp	Sec	Ohm	Ohm
FSMD010-R	0.10	0.30	60.0	100	8.0	8.0	0.020	1.600	15.000
FSMD014-R	0.14	0.30	60.0	100	0.8	8.0	0.008	1.200	6.500
FSMD020-R	0.20	0.40	30.0	100	0.8	8.0	0.020	0.800	5.000
FSMD020-60-R	0.20	0.40	60.0	100	0.8	8.0	0.020	0.800	5.000
FSMD030-R	0.30	0.60	30.0	100	0.8	8.0	0.100	0.200	1.750
FSMD035-R	0.35	0.70	16.0	100	0.8	8.0	0.100	0.320	1.500
FSMD035-30-R	0.35	0.70	30.0	100	0.8	8.0	0.100	0.320	1.500
FSMD050-R	0.50	1.00	16.0	100	0.8	8.0	0.150	0.150	1.000
FSMD050-30-R	0.50	1.00	30.0	100	8.0	8.0	0.150	0.150	1.000
FSMD075-R	0.75	1.50	16.0	100	0.8	8.0	0.200	0.110	0.450
FSMD075-24R	0.75	1.50	24.0	100	1.0	8.0	0.200	0.110	0.290
FSMD075-33R	0.75	1.50	33.0	100	1.0	8.0	0.200	0.110	0.400
FSMD110-R	1.10	2.20	8.0	100	8.0	8.0	0.300	0.040	0.210
FSMD110-16-R	1.10	2.20	16.0	100	8.0	8.0	0.500	0.060	0.180
FSMD110-24R	1.10	2.20	24.0	100	1.0	8.0	0.500	0.060	0.200
FSMD110-33R	1.10	2.20	33.0	100	8.0	8.0	0.500	0.060	0.200
FSMD125-R	1.25	2.50	6.0	100	8.0	8.0	0.400	0.050	0.140
FSMD125-16R	1.25	2.50	16.0	100	8.0	8.0	0.400	0.050	0.140
FSMD150-R	1.50	3.00	8.0	100	8.0	8.0	0.500	0.040	0.110
FSMD150-12R	1.50	3.00	12.0	100	1.0	8.0	0.500	0.040	0.110
FSMD150-24R	1.50	3.00	24.0	100	1.0	8.0	1.500	0.040	0.120
FSMD160-R	1.60	3.20	8.0	100	8.0	8.0	0.500	0.030	0.100
FSMD160-12R	1.60	3.20	12.0	100	1.0	8.0	1.000	0.030	0.100
FSMD160-16R	1.60	3.20	16.0	100	1.0	8.0	1.000	0.030	0.100
FSMD160-24R	1.60	3.20	24.0	100	1.0	8.0	1.000	0.030	0.100
FSMD200R	2.00	3.50	8.0	100	1.0	8.0	2.000	0.020	0.070
FSMD200-16R	2.00	3.50	16.0	100	1.0	8.0	5.000	0.020	0.085
FSMD260R	2.60	5.00	8.0	100	1.0	8.0	2.500	0.015	0.047

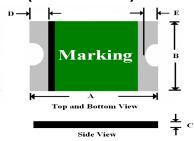
NOTE: Specification subject to change without notice. 2021/03/23

RFE FUZETEC	NO.	PQ04-01ER		
Product Specification and Approval Sheet	Version	1	Page	2/5

FSMD260-13R	2.60	5.00	13.2	100	1.3	8.0	5.000	0.015	0.050
FSMD260-16R	2.60	5.00	16.0	100	1.3	8.0	5.000	0.015	0.050
FSMD300R	3.00	5.00	6.0	100	1.0	8.0	4.000	0.012	0.040

I_H=Hold current-maximum current at which the device will not trip at 23℃ still air.

4. FSMD Product Dimensions (Millimeters)



Part	-	4	E	3	([)	E	<u> </u>
Number	Min.	Max.								
FSMD010-R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
FSMD014-R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
FSMD020-R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
FSMD020-60-R	4.37	4.73	3.07	3.41	0.60	0.90	0.30	0.95	0.25	0.65
FSMD030-R	4.37	4.73	3.07	3.41	0.40	0.70	0.30	0.95	0.25	0.65
FSMD035-R	4.37	4.73	3.07	3.41	0.40	0.70	0.30	0.95	0.25	0.65
FSMD035-30-R	4.37	4.73	3.07	3.41	0.40	0.70	0.30	0.95	0.25	0.65
FSMD050-R	4.37	4.73	3.07	3.41	0.35	0.65	0.30	0.95	0.25	0.65
FSMD050-30-R	4.37	4.73	3.07	3.41	0.45	0.75	0.30	0.95	0.25	0.65
FSMD075-R	4.37	4.73	3.07	3.41	0.35	0.65	0.30	0.95	0.25	0.65
FSMD075-24R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
FSMD075-33R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
FSMD110-R	4.37	4.73	3.07	3.41	0.25	0.55	0.30	0.95	0.25	0.65
FSMD110-16-R	4.37	4.73	3.07	3.41	0.25	0.90	0.30	0.95	0.25	0.65
FSMD110-24R	4.37	4.73	3.07	3.41	0.80	1.30	0.25	0.95	0.25	0.65
FSMD110-33R	4.37	4.73	3.07	3.41	0.80	1.30	0.25	0.95	0.25	0.65
FSMD125-R	4.37	4.73	3.07	3.41	0.25	0.55	0.30	0.95	0.25	0.65
FSMD125-16R	4.37	4.73	3.07	3.41	0.50	1.00	0.30	0.95	0.25	0.65
FSMD150-R	4.37	4.73	3.07	3.41	0.25	0.55	0.30	0.95	0.25	0.65
FSMD150-12R	4.37	4.73	3.07	3.41	0.60	1.10	0.25	0.95	0.25	0.65
FSMD150-24R	4.37	4.73	3.07	3.41	0.60	1.55	0.25	0.95	0.25	0.65
FSMD160-R	4.37	4.73	3.07	3.41	0.25	0.90	0.30	0.95	0.25	0.65
FSMD160-12R	4.37	4.73	3.07	3.41	0.60	1.35	0.25	0.95	0.25	0.65
FSMD160-16R	4.37	4.73	3.07	3.41	0.60	1.35	0.25	0.95	0.25	0.65
FSMD160-24R	4.37	4.73	3.07	3.41	0.55	1.20	0.25	0.95	0.25	0.65
FSMD200R	4.37	4.73	3.07	3.41	0.55	1.20	0.25	0.95	0.25	0.65
FSMD200-16R	4.37	4.73	3.07	3.41	0.60	1.55	0.25	0.95	0.25	0.65
FSMD260R	4.37	4.73	3.07	3.41	0.55	1.20	0.25	0.95	0.25	0.65

NOTE: Specification subject to change without notice.

I_T=Trip current-minimum current at which the device will always trip at 23° still air.

V_{MAX}=Maximum voltage device can withstand without damage at it rated current (I_{MAX}).

I_{MAX}= Maximum fault current device can withstand without damage at rated voltage (V_{MAX}).

Pd=Typical power dissipated-type amount of power dissipated by the device when in the tripped state in 23°C still air environment.

R_{MIN}=Minimum device resistance at 23°C prior to tripping.

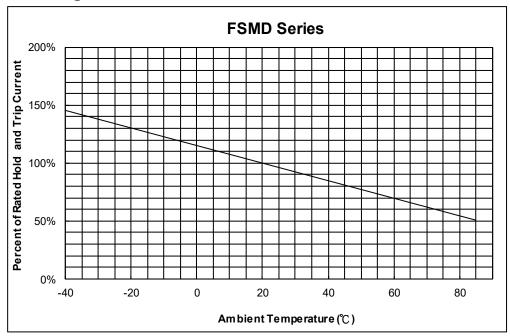
R1_{MAX}=Maximum device resistance at 23°C measured 1 hour after tripping or reflow soldering of 260°C for 20 seconds.

Termination pad characteristics

Termination pad materials: Pure Tin

RFE FUZETEC							NO.	PC	Q04-01E	ER
Product S	Specif	icatio	n and	Appro	oval SI	heet	Version	1	Page	3/5
FSMD260-13R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
FSMD260-16R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65
FSMD300R	4.37	4.73	3.07	3.41	0.80	1.55	0.25	0.95	0.25	0.65

5. Thermal Derating Curve





B = FSMD014-R

C = FSMD020-R / 020-60-R

D = FSMD030-R

E = FSMD035-R / 035-30-R

F = FSMD050-R / 050-30-R

G = FSMD075-R / 075-24R / 075-33R

H = FSMD110-R / 110-16-R /

110-24R / 110-33R

I = FSMD125-R / 125-16R

J = FSMD150-R / 150-12R / 150-24R

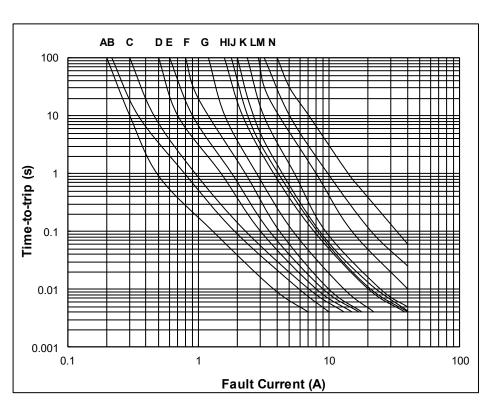
K = FSMD160-R / 160-12R / 160-16R / 160-24R

L = FSMD200R / 200-16R

M = FSMD260R / 260-13R /

260-16R

N = FSMD300R



RFE FUZETEC	NO.	PC	Q04-01I	ĒR
Product Specification and Approval Sheet	Version	1	Page	4/5

7. Material Specification

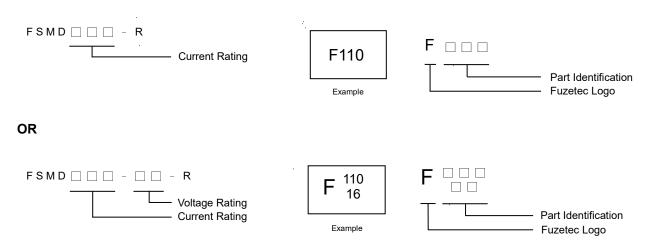
Terminal pad material: Pure Tin

Soldering characteristics: Meets EIA specification RS 186-9E, ANSI/J-std-002 Category 3

8. Part Numbering and Marking System

Part Numbering System

Part Marking System

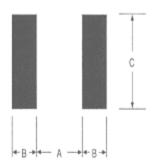


- Warning: Each product should be carefully evaluated and tested for their suitability of application.
 - Operation beyond the specified maximum rating or improper use may result in damage and possible electrical arcing and/or flame.
 - PPTC device are intended for occasional overcurrent protection. Application for repeated overcurrent condition and/or prolonged trip are not anticipated.
 - Avoid contact of PPTC device with chemical solvent, including some inert material such as silicone based oil, lubricant and etc. Prolonged contact will damage the device performance.
 - Additional protection mechanism are strongly recommended to be used in conjunction with the PPTC device for protection against abnormal or failure conditions.
 - Avoid use of PPTC device in a constrained space such as potting material, housing and containers where have limited space to accommodate device thermal expansion and/or contraction.

RFE FUZETEC	NO.	PC	Q04-01I	ĒR
Product Specification and Approval Sheet	Version	1	Page	5/5

9. Pad Layouts . Solder Reflow and Rework Recommendations

The dimension in the table below provide the recommended pad layout for each FSMD1812 device



Pad dimensions (millimeters)						
Device	A Nominal	B Nominal	C Nominal			
	NOIIIIIai	Nominai	Nommai			
All 1812 Series	3.45	1.78	3.50			

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (Tsmax to Tp)	3 °C/second max.
Preheat:	
Temperature Min (Tsmin)	150 ℃
Temperature Max (Tsmax)	200 ℃
Time (tsmin to tsmax)	60-180 seconds
Time maintained above:	
Temperature(T _L)	217 ℃
Time (t∟)	60-150 seconds
Peak/Classification Temperature(Tp):	260 ℃
Time within 5℃ of actual Peak:	
Temperature (tp)	20-40 seconds
Ramp-Down Rate:	6 °C/second max.
Time 25 ℃ to Peak Temperature:	8 minutes max.
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Note 1: All temperatures refer to of the package, measured on the package body surface.

Solder reflow

- Due to "Lead Free" nature, Temperature and Dwelling time for the soldering zone is higher than those for Regular. This may cause damage to other components.
- Recommended max paste thickness is 0.25mm.(Nominal)
- 2. Devices can be cleaned using standard methods and aqueous solvent.
- 3. Rework use standard industry practices.
- 4. Storage Environment: < 30°C / 60%RH Caution:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

2. Devices are not designed to be wave soldered to the bottom side of the board.

Reflow Profile

